

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	16	Giri.in. and chip with module	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2005/08/04 10:32
L2	60	29/830-832.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder)	USPAT; EPO; JPO	OR	ON	2005/08/04 10:40
L3	0	"29"/\$.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and frame with stiffen\$3	USPAT; EPO; JPO	OR	ON	2005/08/04 10:41
L4	46	"29"/\$.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and frame	USPAT; EPO; JPO	OR	ON	2005/08/04 10:42
L5	137	"257"/\$.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and frame	USPAT; EPO; JPO	OR	ON	2005/08/04 10:43
L6	66	"257"/690-790.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and frame	USPAT; EPO; JPO	OR	ON	2005/08/04 10:46
L7	21	"174"/250-266.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and frame	USPAT; EPO; JPO	OR	ON	2005/08/04 10:47
L8	60	"361"/600-800.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4) near3 (carrier plate holder) and frame	USPAT; EPO; JPO	OR	ON	2005/08/04 10:49
L9	165	"29"/825-854.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4 sacrificial) near3 (carrier plate holder)	USPAT; EPO; JPO	OR	ON	2005/08/04 10:56
L10	32	"257"/778.ccls. and (thin\$1film multi\$1layer) near3 (structure board substrate) and (temporary remov\$4 detach\$4 sacrificial) near3 (carrier plate holder)	USPAT; EPO; JPO	OR	ON	2005/08/04 10:57

L11	25	"257"/\$.ccls. and thin\$1film near3 (structure board substrate multi\$1layer layer) and (temporary remov\$4 detach\$4 sacrificial) near3 (carrier plate holder) and frame	USPAT; EPO; JPO	OR	ON	2005/08/04 10:58
L12	7	"174"/\$.ccls. and thin\$1film near3 (structure board substrate multi\$1layer layer) and (temporary remov\$4 detach\$4 sacrificial) near3 (carrier plate holder) and frame	USPAT; EPO; JPO	OR	ON	2005/08/04 10:59
L13	6	"361"/\$.ccls. and thin\$1film near3 (structure board substrate multi\$1layer layer) and (temporary remov\$4 detach\$4 sacrificial) near3 (carrier plate holder) and (carrier frame)	USPAT; EPO; JPO	OR	ON	2005/08/04 10:59